

IN THE SPECIFICATION

Please replace paragraph 27 with the following rewritten paragraph:

Figures 1, 2A and 2B show an embodiment of a plasma processing device 10. A vacuum pump (not shown) reduces the pressure within a process chamber 12. The vacuum pump is connected to the process chamber by a vacuum port 14, which can be located anywhere around the process chamber 12 such that a sufficient vacuum can be created within the process chamber 12 by the vacuum pump. After a sufficiently low pressure is established, at least one process gas enters a process chamber 12 through gas inlet ports [[14]] (not shown) in an upper electrode assembly 13.